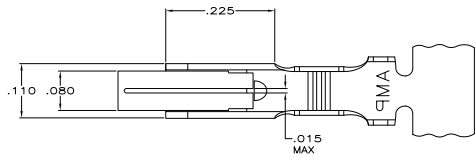
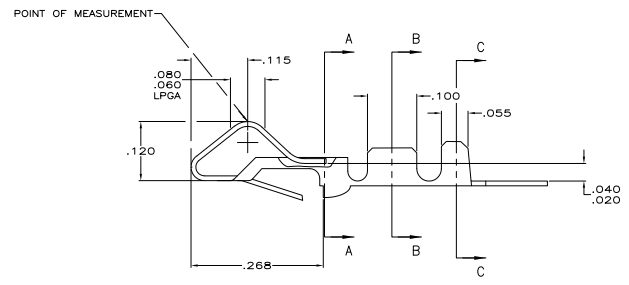
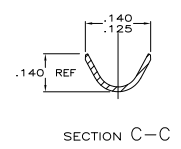
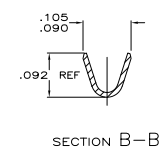
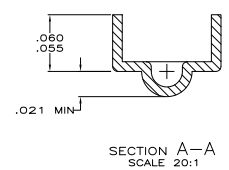


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REV	DATE	DESCRIPTION	BY	CHK
00				
AS1		REVISED PER ECD-11-00927	11MM11	RK/HMR



- △ .000080 - .000200 TIN OVER .000050 MIN NICKEL
- 2. INSULATION RANGE: .100 DIA MAX.  
WIRE RANGE :24-18 AWG (0.02 - 0.9 MM<sup>2</sup>).
- △ .000080 - .000200 TIN-LEAD OVER .000050 MIN NICKEL
- △ .000050 NICKEL OVERALL WITH .000030 MIN GOLD IN THE LOCALIZED GOLD PLATE AREA (LPGA).



-	△	.012 BRASS	3-61668-1
-	△	.012 PH BRZ	61668-4
-	△	PRE-TIN .012 PH BRZ	61668-2
-	△	.012 BRASS	61668-1

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FRACTIONS		DR. ELLIS	ENG0903		
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CUSTOMER DRAWING		DATE	ISSUE	DATE	ISSUE
		A1	00779	G	61668
		SCALE	10:1	SHEET	1 OF 1
					AS1